



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-02-26
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD7N65M2	TLDP*MQF0B62	A	SHENZHEN B/E	2016-02-26
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5, 6.1, 2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLPD*MQF0862					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.484	mg	supplier	die	Silicon (Si)	7440-21-3		3.345	mg	960115	10139
				supplier	metallization	Aluminium (Al)	7429-90-5		0.066	mg	18938	200
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	4591	48
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	6887	73
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	574	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	6600	70
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.008	mg	2296	24
Leadframe	Copper & its alloys	166.150	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	497430
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1986	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2781	1400
				supplier	metallization	Nickel (Ni)	7440-02-0		1.199	mg	7216	3633
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	21
Soft solder	Solder	3.354	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.203	mg	954979	9706
				supplier	solder	Silver (Ag)	7440-22-4		0.084	mg	25045	255
				supplier	solder	Tin (Sn)	7440-31-5		0.067	mg	19976	203
Bonding wires	Other inorganic materials	0.449	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.448	mg	998885	1358
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	1115	2
				supplier	wire							
Encapsulation	Other Organic Materials	155.518	mg	supplier	mold compound	Silica, vitreous	60676-86-0		136.077	mg	874992	412355
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		6.221	mg	40002	18852
				supplier	mold compound	Epoxy Resin	25068-38-6		4.666	mg	30003	14139
				supplier	mold compound	phenol resin	29690-82-2		7.776	mg	50001	23564
				supplier	mold compound	Carbon black	1333-86-4		0.778	mg	5003	2358
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167